

AMENDMENTS TO THE ABSTRACT

A fabrication cooling apparatus for a wafer baking plate is provided. The wafer baking plate has a support plate for supporting a wafer, a heater under the support plate, and a heat transfer plate interposed between the support plate and the heater, for transferring heat. In the fabrication cooling apparatus, a hollow bore is formed in the heat transfer plate of the wafer baking plate and partially filled with a liquid working fluid. A cooling pipe is laid in the heat transfer plate, for circulating a cooling medium. The wafer baking plate is cooled down via the working fluid, stabilizing its temperature distribution. Therefore, the product yield of wafers is increased.